



## Advances in Tangible and Embodied Interaction for Virtual and Augmented Reality

Guest Editors:

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**Dr. Pedro Martins**

Deadline for manuscript  
submissions:

**closed (15 January 2023)**

### Message from the Guest Editors

For this Special Issue, we are interested in gathering research that bridges atoms and bits in virtual and augmented environments. Basic research papers that demonstrate new interaction technologies or techniques, descriptions of applications that use tangibles in VR/AR in any domain, and survey papers that can help structure and systematize current knowledge on this area are all suitable. Topics of interest include, but are not limited to:

- Technologies for object detection/recognition in AR
- Interaction techniques that use tangibles/embodied interactions
- Haptic systems and interactions for VR/AR
- Authoring systems
- Programming libraries, toolkits, and frameworks
- Applications in cultural heritage, medicine, rehabilitation, gaming, entertainment, teaching, training, visualization, etc.
- Design methodologies
- Evaluation methodologies





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## Editor-in-Chief

### **Prof. Dr. Flavio Canavero**

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## Message from the Editor-in-Chief

*Electronics* is a multidisciplinary journal designed to appeal to a diverse audience of research scientists, practitioners, and developers in academia and industry. The journal is devoted to fast publication of latest technological breakthroughs, cutting-edge developments, and timely reviews of current and emerging technologies related to the broad field of electronics. Experimental and theoretical results are published as regular peer-reviewed articles or as articles within Special Issues guest-edited by leading experts in selected topics of interest.

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